

Electronic Acknowledgement Receipt

EFS ID:	1423305
Application Number:	10632568
International Application Number:	
Confirmation Number:	2603
Title of Invention:	SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING PACKAGE STACKED OVER BALL GRID ARRAY PACKAGE AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES
First Named Inventor/Applicant Name:	Marcos Karnezos
Customer Number:	22470
Filer:	Bill Kennedy/Paula Hurley
Filer Authorized By:	Bill Kennedy
Attorney Docket Number:	CPAC 1017-3
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Application Type:	Utility

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed	efsidsAA20070108.pdf	59318	no	2

Warnings:

Information:

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Total Files Size (in bytes):

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.